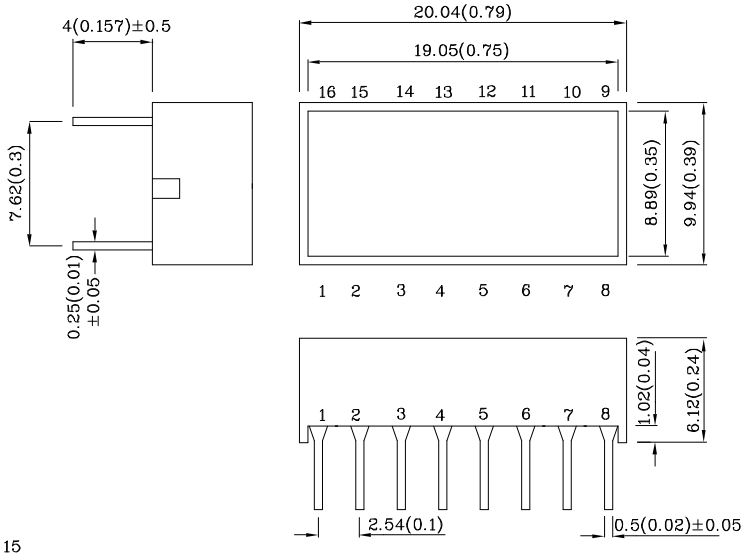
SunLED
www.SunLED.com

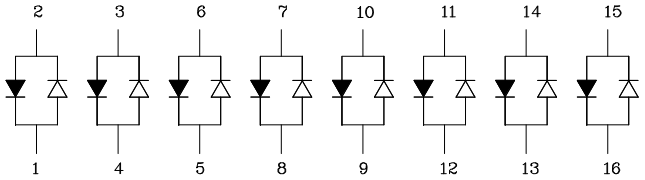
Part Number: **EURMG2885M**

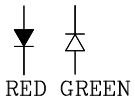
8.89mmx19.05mm LED LIGHT BAR

Features

- UNIFORM LIGHT EMITTING AREA.
- LOW CURRENT OPERATION.
- EASILY MOUNTED ON P.C. BOARDS.
- FLUSH MOUNTABLE.
- EXCELLENT ON/OFF CONTRAST.
- CAN BE USED WITH PANELS AND LEGEND MOUNTS.
- RoHS COMPLIANT.







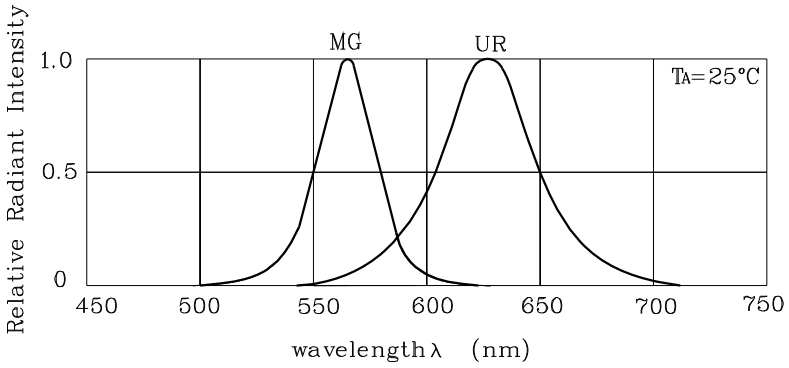
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25(0.01") unless otherwise noted.
3. Specifications are subject to change without notice.

Absolute maximum ratings (T_A=25°C)		**UR (GaAsP/ GaP)**	**MG (GaP)**	**Unit**
Forward Current	I_F	30	25	mA
Forward Current (Peak)	i_{FS}	160	140	mA
Power Dissipation	P_T	75	62.5	mW
Operating Temperature	T_A	-40 ~ +85		°C
Storage Temperature	Tstg	-40 ~ +85		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3~5 Seconds			

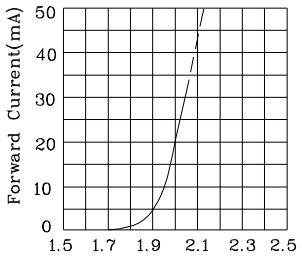
Operating Characteristics (T_A=25°C)		**UR (GaAsP/ GaP)**	**MG (GaP)**	**Unit**
Forward Voltage (Typ.) (I_F=20mA)	V_F	2.0	2.2	V
Forward Voltage (Max.) (I_F=20mA)	V_F	2.5	2.5	V
Wavelength of Peak Emission (Typ.) (I_F=20mA)	λ P	627	565	nm
Wavelength of Dominant Emission (Typ.) (I_F=20mA)	λ D	625	568	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I_F=20mA)	Δλ	45	30	nm
Capacitance (Typ.) (V_F=0V, f=1MHz)	C	15	15	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λ P
				min.	typ.	
EURMG2885M	Red	GaAsP/GaP	White Diffused	18	80.1	627
	Green	GaP		50	117	565

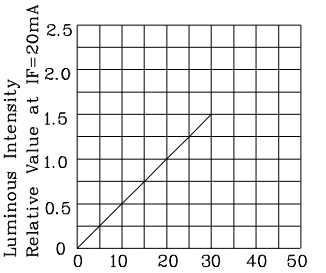


RELATIVE INTENSITY Vs. WAVELENGTH

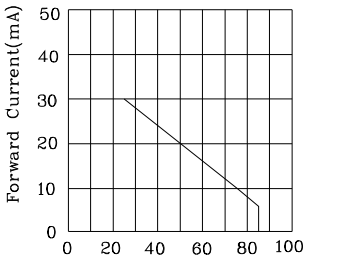
❖ **UR**



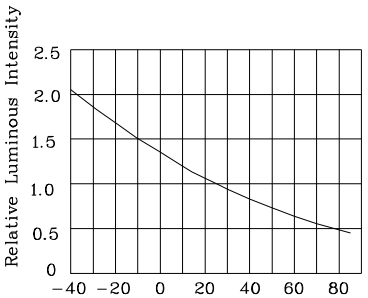
FORWARD CURRENT Vs.
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT

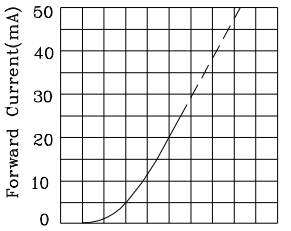


FORWARD CURRENT
DERATING CURVE

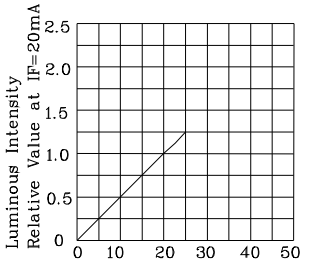


LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

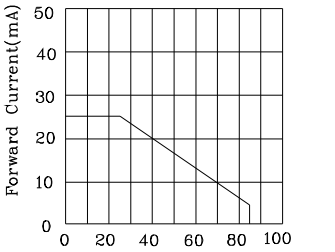
❖ **MG**



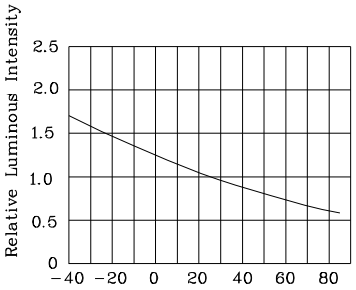
FORWARD CURRENT Vs.
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT



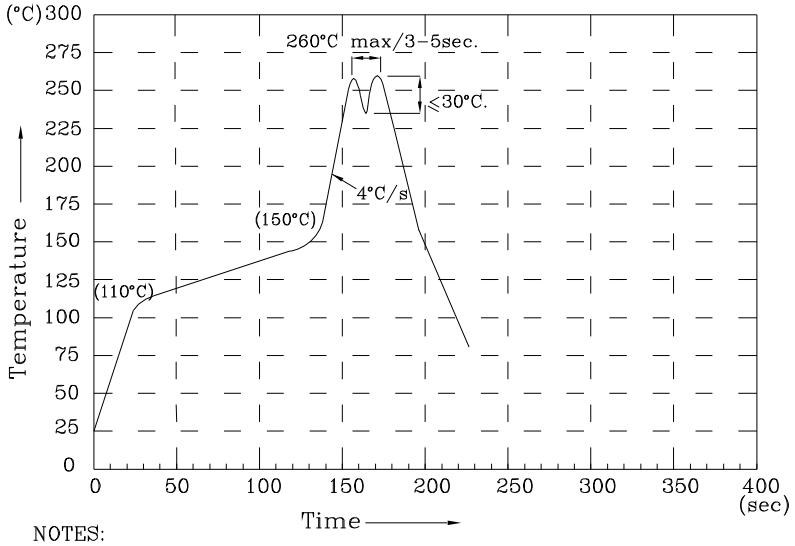
FORWARD CURRENT
DERATING CURVE



LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

EURMG2885M

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
2.Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4.No more than once.

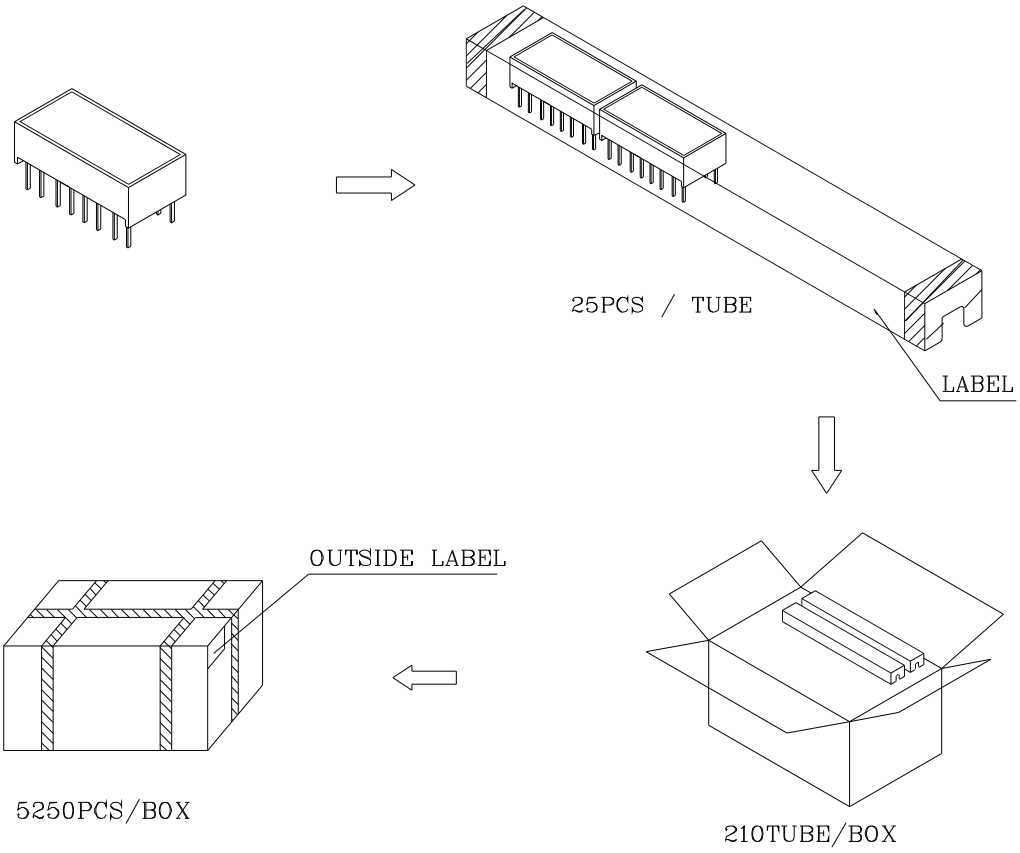
Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

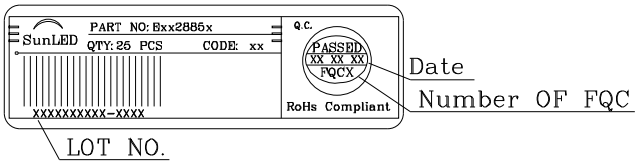
1. Wavelength: +/-1nm
2. Luminous intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS EURMG2885M



Inside LABEL Paste On The IC-tube



Outside LABEL Paste On The Box